

CHANGES TO THE SPECIFICATION

Please substitute the following marked up paragraph(s) for the paragraph(s) now appearing in the currently filed specification:

Page 1, after the Title, please insert the following:

CROSS REFERENCE TO RELATED APPLICATIONS

This application is a continuation of application Serial No. 09/757,964, filed January 10, 2001, which is a divisional of application Serial No. 09/372,547, filed August 11, 1999, now U.S. Patent No. 6,236,558.

Paragraph beginning at page 2, line 18:

2) The cutting surface is not sufficiently flat, and it is difficult to ~~to~~ as a result to provide a narrow resultant space between the outer electrodes.

Paragraph beginning at page 4, line 29:

FIG. 1 is an exploded perspective view showing a multilayer electronic part according to a first embodiment of the present invention. A chip capacitor 10 is a multilayer electronic component and includes a multilayer body 11 composed of a plurality of stacked sheet layers 12a to 12f made of ceramics. The chip capacitor also includes capacitor electrodes 13a to 13e serving as inner electrodes disposed within the multilayer body 11; via hole electrodes 14a, 14b serving as connectors; and outer electrodes 15a and 15b disposed on only the main surfaces 11a and 11b of the multilayer body 11 such that they are electrically connected to the capacitor electrodes 13a and 13e via the via hole electrodes 14a.

Paragraph beginning at page 5, line 12:

In this case, the capacitor electrodes 13a, 13c, and 13e, and the capacitor electrodes 13b and 13d are electrically connected via the via hole electrodes 14a and 14b, respectively.

Paragraph beginning at page 5, line 29:

Next, through holes 22 are formed in the mother sheet layers 21 to 21f by way of, for example, punching, and the capacitor electrodes 13a to 13e are formed on the mother sheet layers 21b to 21f, respectively, for example by screen-printing conductive paste thereon. Further, the via hole electrodes 14a, 14b are formed by disposing conductive paste in the through holes 22 (FIG. 3B).

Paragraph beginning at page 6, line 3:

After a mother multilayer body 23 is formed by layering the plurality of mother sheet layers 21a to 21f on top of one another, conductive paste is screen-printed on only the main surfaces 23a and 23b of the mother multilayer body 23 such that the outer electrodes 15a and 15b are formed thereon. In this case, the capacitor electrodes 13a to 13e on the mother sheet layers 21b to 21f, and the outer electrodes 15a and 15b on the main surfaces 23a and 23b of the mother multilayer body 23 are connected via the via hole electrodes 14a. Since the mother multilayer body 23 has not yet been subjected to cutting, the main surfaces 23a and 23b thereof with outer electrodes 15a and 15b have a high level of flatness (FIG. 3C).

Paragraph beginning at page 6, line 17:

Next, the mother multilayer ~~11~~ body 23, provided with the capacitor electrodes 13a to 13e therein and the outer electrodes 15a and 15b on the main surfaces 23a and 23b

thereof, is cut into blocks, each of which is to become a separate multilayer body 11.

Subsequently, the multilayer body 11, the capacitor electrodes 13a to 13e, the via hole electrodes 14a, 14b, and the outer electrodes 15a and 15b are baked together (FIG. 3D).